

## IN-SITU POLISHING PAD FLATNESS CONTROL

### ABSTRACT

Conditioning of a polishing pad so as to control the surface profile and achieve uniformity in wear of a polishing pad (18) by causing the workpiece (11) and polishing pad (18) to oscillate radially relative to one another with the extent of the oscillating movement being sufficient so that the workpiece (11) extends over the edges of the polishing pad (18).

Fig. 1.

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